1. BASE



Features

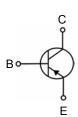
- Ideally suited for automatic insertion
- For switching and AF amplifier applications



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
BC846/BC847 /BC848	SOT-23	1x	3000

x: BC846A=A; BC846B=B; BC846C=C; BC847A=E; BC847B=F; BC847C=G; BC848A=J; BC848B=K; BC848C=L.



Maxmim Ratings (Ta=25 unless otherwise noted)

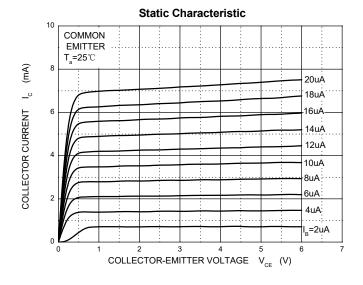
Symbol	Parameter		Limit	Unit
	Collector-Base Voltage	BC846	80	
V _{CBO}		BC847	50	V
		BC848	30	
	Collector-Emitter Voltage	BC846	65	
V _{CEO}		BC847	45	V
		BC848	30	
V _{EBO}	Emitter-Base Voltage		6	V
I _c	Collector Current		100	mA
P _c	Collector Power Dissipation		200	mW
R _{OJA}	Thermal Resistance From Junction To Ambient		625	°CW
T _j	Junction Temperature		150	°C
T _{stg}	Storage Temperature		-55∼+150	°C

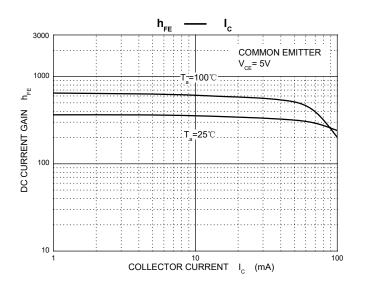


Electrcal Charcteristics (Ta=25 unless otherwise specified)

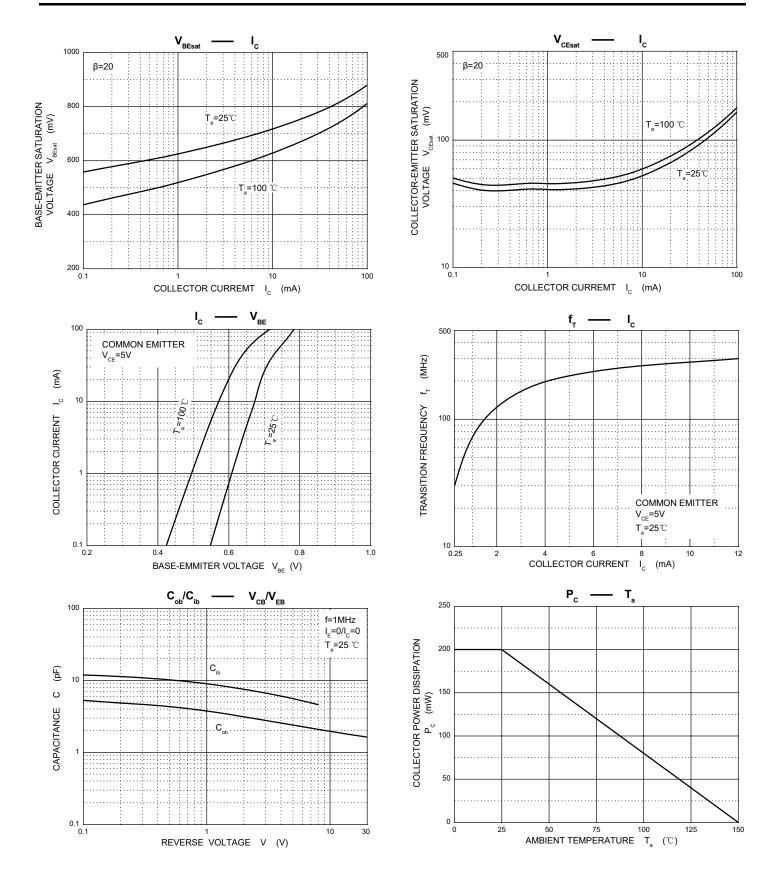
Symbol	Parameter		Test conditions	Min	Max	Unit
V _{(BR)CBO}	Collector-base breakdown voltage	BC846 BC847 BC848	I _C =10μΑ, I _E =0	80 50 30		V
V _{(BR)CEO}	Collector-emitter breakdown voltage	BC846 BC847 BC848	I _C =10mA, I _B =0	65 45 30		V
V _{(BR)EBO}	Emitter-base breakdown voltage		I _E =10μΑ, I _C =0	6		V
I _{CBO}	Collector cut-off current	BC846 BC847 BC848	V _{CB} =70V, I _E =0 V _{CB} =50V, I _E =0 V _{CB} =30V, I _E =0		100	nA
I _{EBO}	Emitter cut-off current		V _{EB} =5V, I _C =0		100	nA
h _{FE}	DC current gain	BC846A BC847A BC848A BC846B BC847B BC848B BC846C BC847C BC848C	V _{CE} =5V, I _C =2mA	110 200 420	220 450 800	
V _{CE(sat)}	Collector-emitter saturation voltage		L =400m A L =5m A		0.5	V
V _{BE(sat)}	Base-emitter saturation voltage		I _C =100mA, I _B =5mA		1.1	V
f⊤	Transition frequency		V _{CE} =5V, I _C =10mA, f=30MHz	100		MHz
Cob	Collector output capacitance		V _{CB} =10V,f= 1MHz		4.5	pF

Typical Characteristics



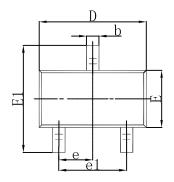


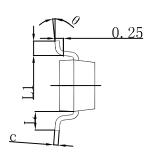


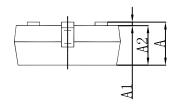




SOT-23 Package Outline Dimensions

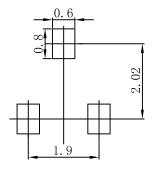






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note:

- 1. Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

BC846/BC847/BC848 NPN Plastic-Encapsulate Transistors

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